

**Attempt all questions of Part-A and Part-B**

**Part – A (40 marks) (to be answered tentatively in 1 hour 20 minutes)**

Q.1(a) What are the characteristics of non-traditional machining processes that make them different from conventional machining processes? [3 marks]

Q.1(b) What are the different types of masks used in chemical machining and where are they used? [3 marks]

Q.2(a) Justify the following in brief.

- (i) De-ionized water is preferred to hydro-carbon oil when used as a dielectric fluid for wire cut EDM.
- (ii) Tungsten-copper electrode is preferred while drilling small and high accuracy holes through die-sinking EDM.
- (iii) Presence of recast layer for die-sinking EDM may be significant whereas that for wire-EDM is negligible.
- (iv) A pulsed DC supply (and not a continuous DC supply) is used in EDM.
- (v) When a ferrous work piece is to be machined with a copper tool in EDM, work piece is connected to the negative terminal for higher productivity.
- (vi) Orbital cutting arrangement of EDM helps in machining complex shapes.

(2.5 x 6 = 15 marks)

Q.2(b) For a die-sinking EDM having R-C type pulse generator, following data are given.

Charging resistance=40 Ohm, C=15  $\mu$ F, Supply voltage= 150 V, Breakdown voltage=120 V, Resistance of the discharge circuit 15 Ohm. The condenser is discharged to a voltage of 5 V during deionization. Calculate

- (i) Charging time before break down takes place,
- (ii) Minimum charging current,
- (iii) Pulse on time of the EDM machine,
- (iv) Maximum discharge current, and
- (v) Duty factor of the EDM set up.

(1x5=5 marks)

Q.3(a) Prove that the inter-electrode gap during die-sinking electrochemical machining (ECM), for a given tool feed rate, eventually attains an equilibrium value irrespective of the initial gap setting.

[8 marks]

Q.3(b) An iron workpiece is machined in an ECM die-sinking machine using a copper tool and aqueous NaCl solution as electrolyte. The copper electrode has a uniform

interaction area of  $100 \text{ cm}^2$ . A constant working gap of  $0.05 \text{ cm}$  is maintained. The ECM machine has a supply voltage of  $25 \text{ V}$ . Specific resistance of the electrolyte is  $5.0 \text{ ohm-cm}$ . For iron, atomic weight =  $56$ , valency =  $2$ , density =  $7.8 \text{ g/cm}^3$ . Faraday's constant =  $96500 \text{ Coulomb}$ . A current efficiency of  $100\%$  may be assumed. Neglect over-voltages at the electrodes.

Calculate the (i) Material removal rate and (ii) Electrode feed rate.

[4+2 =6 marks]

**PART B (20 marks) (to be answered tentatively in 40 minutes)**

1. State whether the following statements are true or false. Justify your answer in a few sentences. [5x2=10]

- i. Material removal processes in electron beam machining (EBM) and focused ion beam machining (FIBM) are different.
- ii. The depth of penetration of EB in a material is constant irrespective of the accelerating voltage and type of material.
- iii.  $\text{Ga}^+$  is commonly used in FIB machine.
- iv. The method of producing  $e^-$  in EBM and  $\text{Ga}^+$  ions in FIB is the same.
- v. The torch of TIG and that of Plasma arc welding machine have the same construction.

2. An open slit of  $500 \text{ }\mu\text{m}$  width in a  $500 \text{ }\mu\text{m}$  thick tungsten sheet is to be cut with an e-beam focused to  $500 \text{ }\mu\text{m}$  diameter. What should be the e-beam powder and machining speed for cutting the slit without any heat affected zone? The thermal diffusivity of tungsten and the specific power for E-beam machining of tungsten are  $6 \times 10^{-5} \text{ m}^2/\text{s}$  and  $12 \text{ W/mm}^3/\text{min}$  respectively. [5 marks]

3. The sputtering rate in a focused ion beam machining is given by

$$V(\text{nm/s}) = 100.S(M/d) J. \cos\theta$$

where, S - sputtering yield (atoms/ion), M - atomic (molecular) weight (g) of target,  
d - target density ( $\text{g/cm}^3$ ), J - ion current density ( $\text{A/cm}^2$ ) and  
 $\theta$  - angle of incidence

A  $10 \text{ }\mu\text{m} \times 10 \text{ }\mu\text{m}$  square and  $1 \text{ }\mu\text{m}$  deep cavity is to be made in a silicon wafer with a focused  $\text{Ga}^+$  ion beam at a  $10^\circ$  angle of incidence. The sputtering yield of ions accelerated at  $30 \text{ kV}$  and incident at the  $10^\circ$  angle is  $10$ . Estimate the machining time to make the cavity at  $10 \text{ nA}$  ion current.

Silicon atomic weight =  $28 \text{ g}$  and density =  $2.34 \text{ g/cm}^3$ .

[5 marks]

\*\*\* End of question paper \*\*\*